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by Amendment

## ABSTRACT

The present invention provides a method of forming a dielectric layer containing dielectric filler, which is excellent in uniformity of a film-thickness, with the use of dielectric filler-containing dielectric layer. In particular, for example, it is a method of forming a dielectric filler-containing polyimide coating on a metallic material through an electrodeposition coating method with the use of a dielectric filler-containing polyimide electrodeposition solution, said solution being a polyimide electrodeposition solution in which a dielectric filler has been contained, wherein the used as a dielectric filler is a globoid dielectric powder having perovskite structure which is 0.05 to 1.0  $\mu\text{m}$  in an average particle size  $D_{1A}$ , 0.1 to 2.0  $\mu\text{m}$  in a weight cumulative particle size  $D_{50}$  based on a laser diffraction scattering particle size distribution measurement method, and 4.5 or less in a coagulation degree value represented by  $D_{50}/D_{1A}$  where the weight cumulative particle size  $D_{50}$  and the average particle size  $D_{1A}$  obtained from an image analysis.